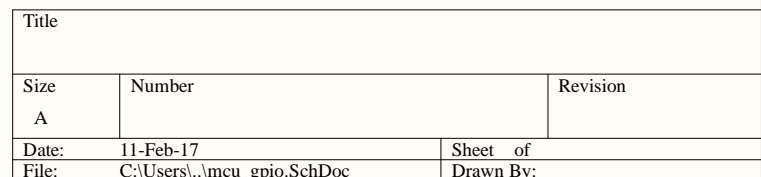
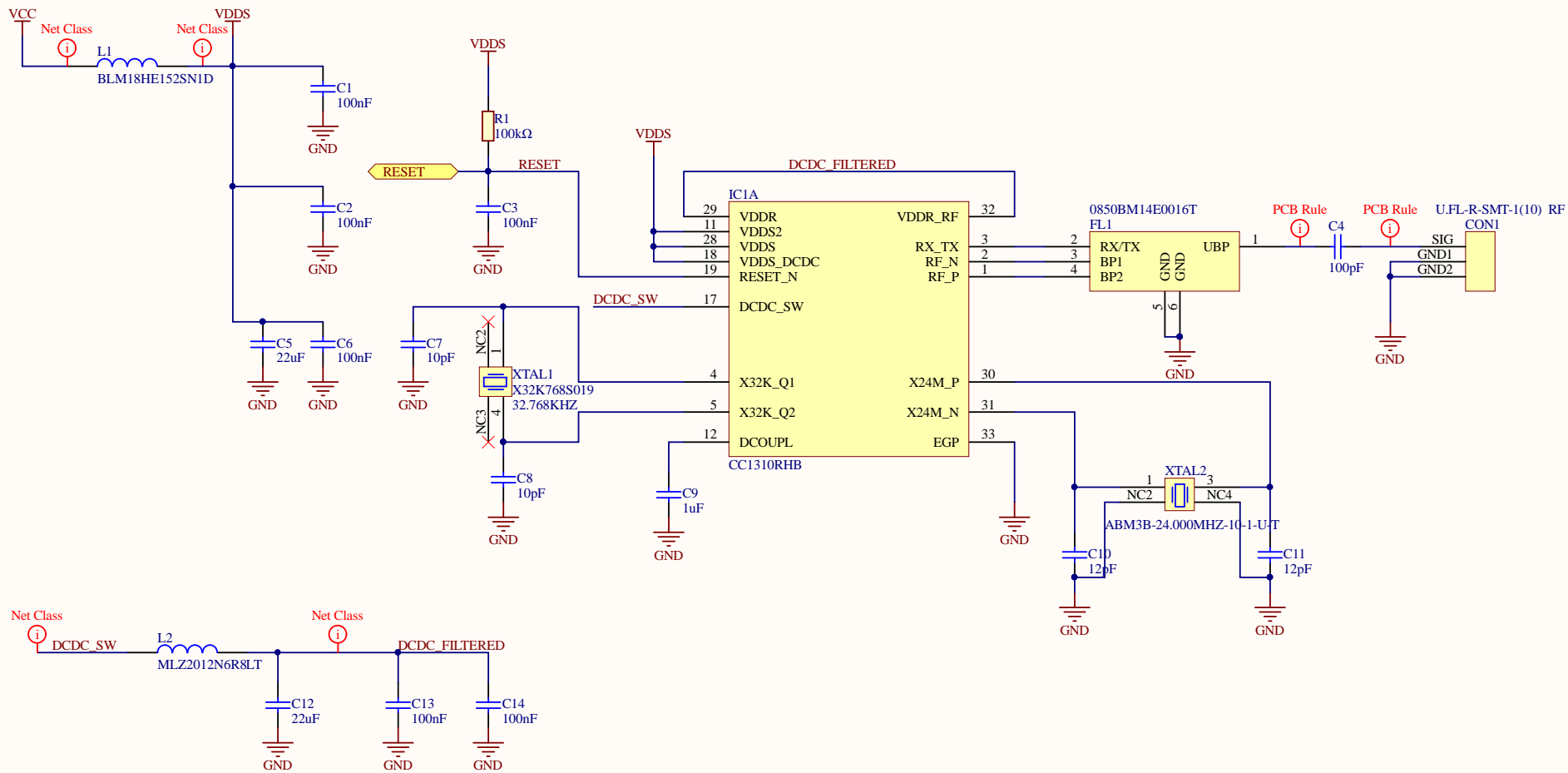


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Date:	11-Feb-17	Sheet of
File:	C:\Users\...\board_connectors.SchDoc	Drawn By:



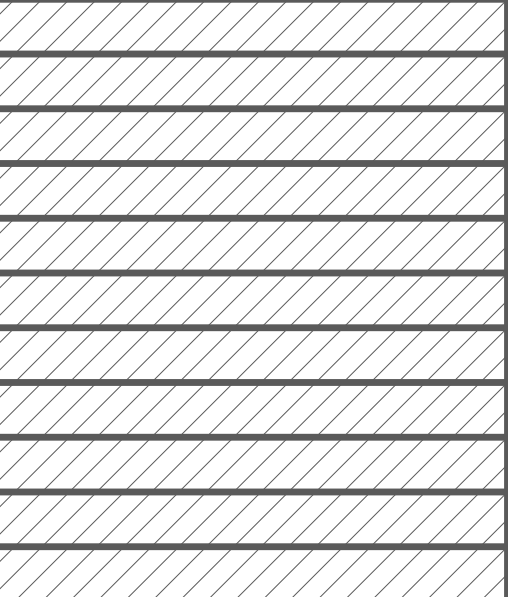


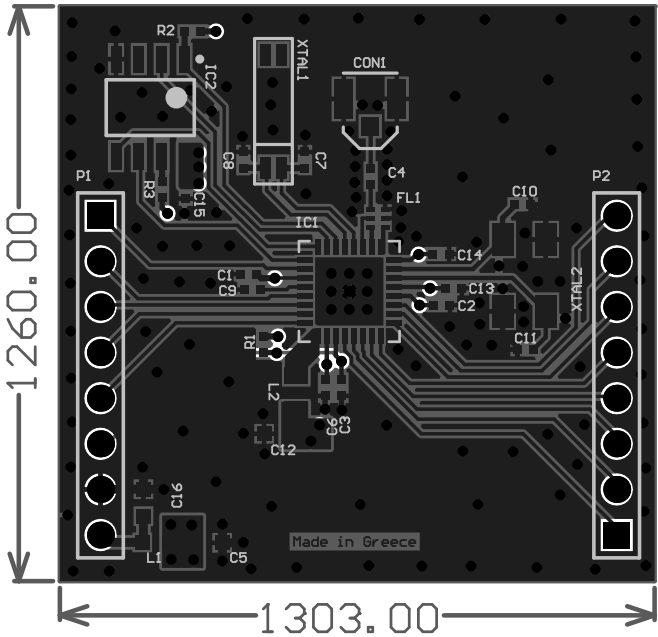
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Date:	11-Feb-17	Sheet of
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B							B
C							C
D							D
1		2		3		4	

Title		
Size A	Number	Revision
Date:	11-Feb-17	Sheet of
File:	C:\Users\...\Sheet4.SchDoc	Drawn By:

Title		
Size A	Number	Revision
Date:	11-Feb-17	Sheet of
File:	C:\Users\...\Sheet4.SchDoc	Drawn By:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.38mil		
4	Dielectric 1	FR-4	6.89mil	4.29	
5	Ground Plane	Copper	1.38mil		
6	Dielectric 3		44.49mil	3.96	
7	Power Plane	Copper	1.38mil		
8	Dielectric 4		6.89mil	4.2	
9	Bottom Layer	Copper	1.38mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Boards